TO-262 .> / / x N ?ú 3 MOS « | • ’ož

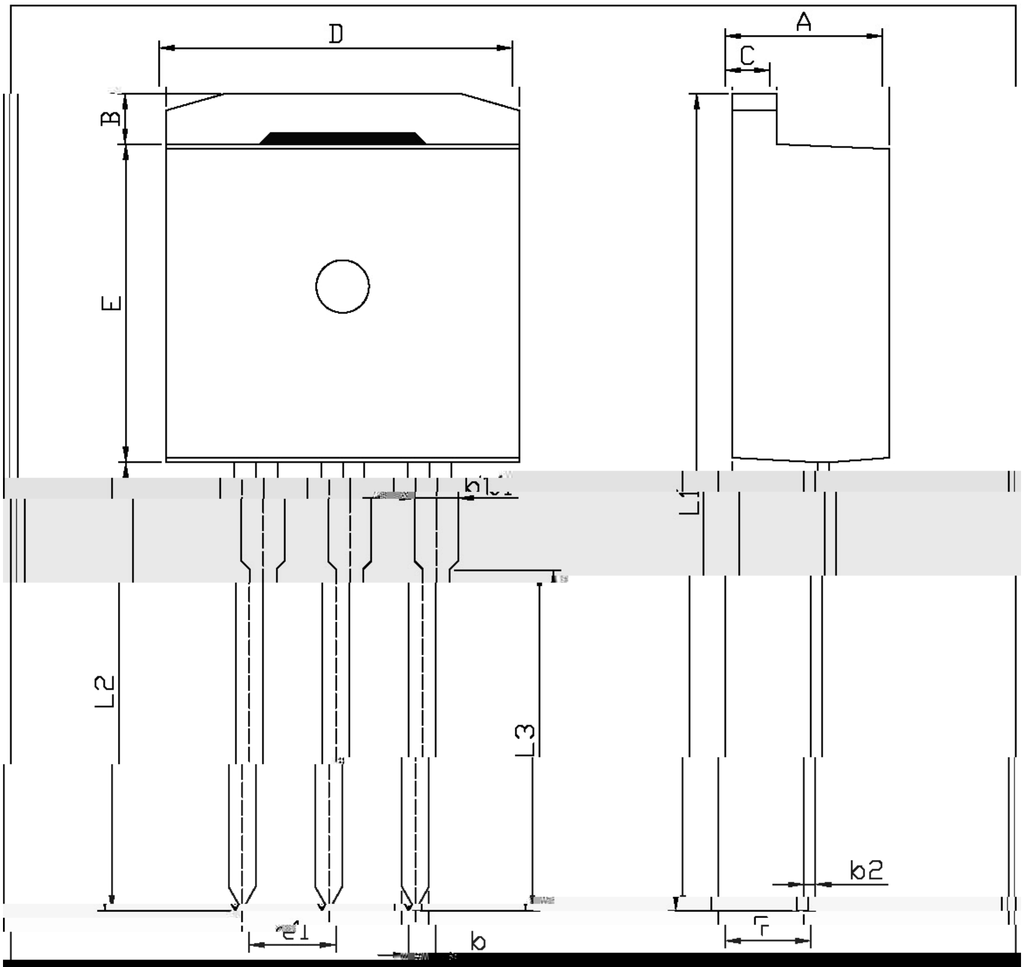
@ ƒ Parameter	… Z Symbol	ƒ › Rating	% y Unit
Drain-Source Voltage	V_{DSS}	650	V
Drain Current	I_D(Tc=25)	7.0	A
Drain Current	I_D(Tc=100)	4.4	A
Drain Current - Pulsed	I_{DM}	28	A
Gate-Source Voltage	V_{GS}	±30	V
Single Pulsed Avalanche Energy	E_{AS}	420	mJ
Repetitive Avalanche Energy	E_{AR}	14.7	mJ
Avalanche Current	I_{AR}	7.0	A
Power Dissipation	P_D(Tc=25)	147	W
Operating and Storage Temperature Range	T_J,T_{ST}		

A-2.6696 -1.34868TD5.45252-c 3074830949b>Tj /T8T4w [(5(A7)

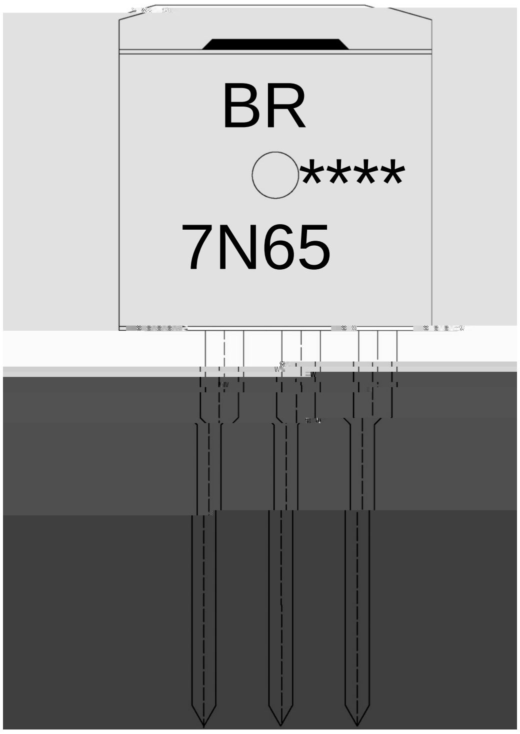
)Gf 383.88 512.3 .48001 18.48 rc47998 18.48 re f BT 10.49584041139-55 to 13

4

Ø ¤ =) ¢ / Package Dimensions



, M y ƒ / Marking Instructions



ª ¢ y

BR y ¸ [W A

4 y º Z W A

y ÿ D Z W A k š ÿ D Z J

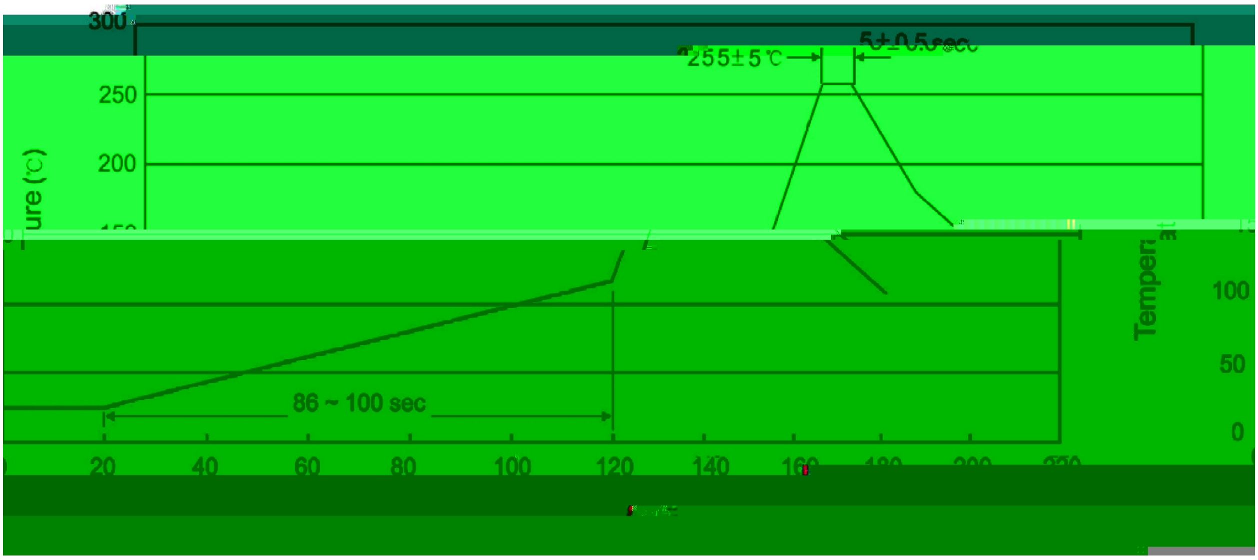
Note:

BR: Company Code

7N65: Product Type

****: Lot No. Code, code change with Lot No

G PD t … • Ž ¢ (x /) / Temperature Profile for Dip Soldering(Pb-Free)



ª ¢ y

1o• Ä ½ “ † 25 ½150 - k ž • 60 ½90sec;

2o• Q › “ † 255 r5 - k ž • 4 Ò 5 r0.5sec;

3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:

1.Preheating:25~150 - , Time:60~90sec.

2.Peak Temp.:255 r5 - , Duration:5 r0.5sec.

3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 270 r5 - ž • y 10 r1 sec.

Temp.:270±5 Time:10±1 sec

G P á / Packaging SPEC.

ì ’ x / TUBE

Package Type 7>û ˜ E	Units ;>û ¦H					Dimension ;>û p . (unit Æmm³)		
	Units/Tube / •1×	Tubes/Inner Box •1× /-	Units/Inner Box /-	Inner Boxes/Outer Box - /1ç	Units/Outer Box /1ç	Tube•1×	Inner Box	Outer Box1ç
TO-262	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

„ Ð y ƒ / Notices